



Rear Silver (A368) Photovoltaic Metallization Paste	Version	1.5
	Issue date	2009/6/3
	Page	1/2

A368 SOLAR CELL REAR SILVER PASTE (LEAD FREE)

PRODUCT DESCRIPTION

This product was specifically designed by GSMC for use as a back contact for silicon solar cells which utilize an aluminum BSF (Back Surface Field). This highly conductive silver composition has excellent adhesion to aluminum backside surfaces.

PRODUCT BENEFITS

- High adhesion with Si wafer and tabbing ribbon
- Complete compatibility with Al paste
- Low resistance
- Good solderability
- Lead & Cadmium -free
- RoHS - compliant

TYPICAL PROPERTIES

Rheology:	Thixotropic, screen printable paste
Appearance	Silver gray
Viscosity:	33±10 kcps (Brookfield DV-II+CPC,#52, 20.0sec-1, 25°C)
Thixotropic Index @ 25°C	4~6 (Brookfield DV-II+CPC, #52, Visc. @ 0.5rpm/Visc. @ 10rpm)
Sheet Resistivity	4±1 mΩ/ sq. at 10um
Solids Content	65%-80%



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	Issue date	2009/6/3
	Page	2/2

PROCESSING SUMMARY

Screen mesh/Emulsion	165-200 mesh / 10-30 μm
Drying	2-3 min at 200-250°C
Printed Thickness	0.14±0.01g at (W4.5mm*L153mm*2Line)
Firing	Furnace: Infrared Heated Zone: 165 inches Set Points: Zone 1-3: 300 °C, Zone 4: 365 °C, Zone 5: 465 °C, Zone 6-8: 550 °C, Zone 9: 600 °C, Zone 10: 810 °C, Zone 11: 920 °C Belt Speed 160 IPM
Peak Firing Temp	700-800°C

TYPICAL FIRING PROFILE

